MATB-405US PATENT

- 21 -

ABSTRACT

A semiconductor device including an organic semiconductor material coupled to a substrate at an interface between the two components. The substrate has a first thermal expansion coefficient. The organic semiconductor material has a second thermal expansion coefficient that is different from the first thermal expansion coefficient. A mechanical stress is transferred from the substrate to the organic semiconductor through the interface, the mechanical stress being related to the difference between the first thermal expansion coefficient and the second thermal expansion coefficient.